

PRODUCT SPECIFICATION

7.0" TFT LCD MODULE

MODEL: YDP LCD I 700 LVDS 001



< ◇ > Preliminary Specification

< ◆ > Finally Specification

CUSTOMER'S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED BY

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2020.05.19	ZJW	Initial Release	
1.1	2020.10.16	YZK	Add Weight Add Chromaticity Transmissive	P4 P6

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	7.0"	
LCD type	IPS TFT	
Display Mode	Transmissive/Normally black	
Resolution	1024 RGB x 600	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	164.9(H) x 100(V) x 3.35(T) (Note1)	mm
Active Area	154.21(H) x 85.92(V)	mm
Pixel Pitch	150.6 (H) x 143.2(V)	um
Pixel Arrangement	RGB vertical Stripe	
Polarizer Surface Treatment	Glare	
Display Colors	262K/16.7 M	
Interface	6/8 bit LVDS Interface	
Driver IC	HX8282-A&HX8696-A	-
With or Without Touch Panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	104	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

V_{SS}=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.5	5.0	V
Storage temperature	T _{STG}	-30	+80	°C
Operating temperature	T _{OP}	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	VDD	2.3	3.3	3.6	V
	VGH	-	17	-	V
	VGL	-	-7	-	V
	VCOM	-	4.2	-	V
Differential input high threshold voltage	RxVTH	-	-	0.1	V
Differential input low threshold voltage	RxVTL	-0.1	-	-	V
Input voltage range (singled-end)	RxVIN	0	-	2.4	V

Note : Typical VCOM is only a reference value. It must be optimized according to each LCM. Please use VR.

5. Backlight Characteristic

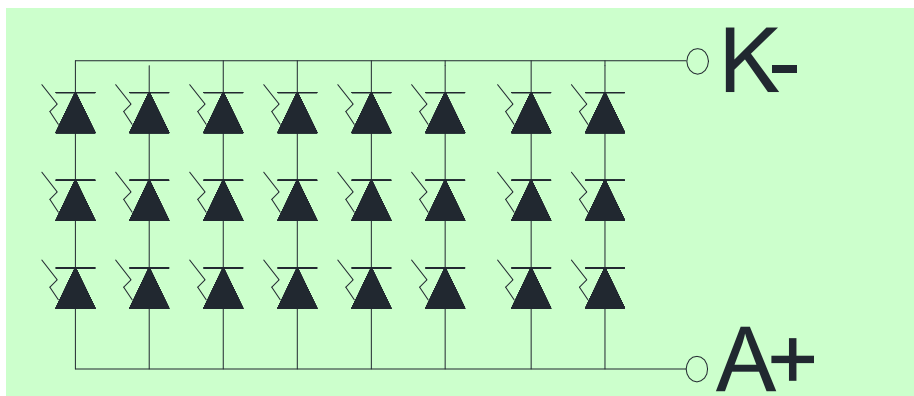
5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	T _a =25 °C, I _F =20mA/LED	8.4	9.6	10.2	V
Forward Current	I _F	T _a =25 °C, V _F =3.2V/LED	-	160	-	mA
Power dissipation	P _D		-	1536	-	mW
Uniformity	Avg		-	80	-	%
LED working life(25°C)	-		-	30,000	-	Hrs
Drive method	Constant current					
LED Configuration	24 White LEDs (3 LEDs in string and 8 groups in parallel)					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at T_a=25±2 °C, 60%RH±5%, I_F=20mA/LED.

5.2. Backlighting circuit



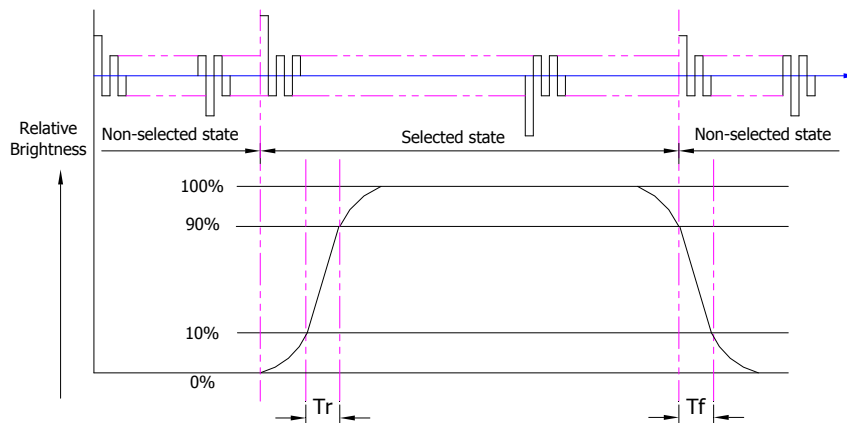
6. Optical Characteristics

Ta=25°C, VDD=3.3V

Backlight On (Transmissive Mode)	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
	Luminance on TFT(I_f =20mA/LED)		Lv		320	400	-	cd/m ²
	Contrast ratio(See 6.3)		CR		800	1000	-	
	Response time (See 6.2)		TR+TF		-	25	35	ms
	Chromaticity Transmissive (See 6.5)	Red	XR		0.537	0.587	0.637	
			YR		0.317	0.367	0.417	
		Green	XG		0.259	0.309	0.359	
			YG		0.535	0.585	0.635	
		Blue	XB		0.093	0.143	0.193	
			YB		0.049	0.099	0.149	
		White	XW		0.243	0.293	0.343	
			YW		0.281	0.331	0.381	
	Viewing Angle (See 6.4)	Horizontal	θX+	Center CR≥10	80	-	-	Deg.
			θX-		80	-	-	
		Vertical	φY+		80	-	-	
			φY-		80	-	-	
NTSC Ratio(Gamut)					45	50	-	%

6.1. Definition of Response Time

6.1.1. Normally Black Type (Negative)

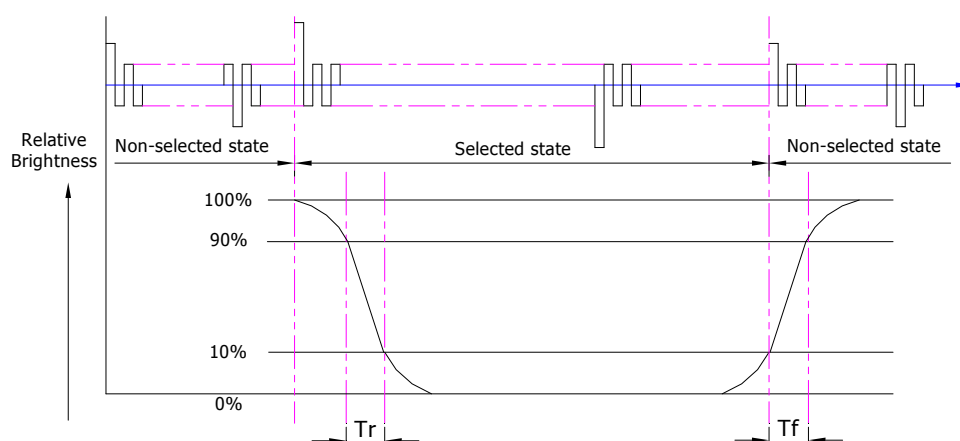


T_r is the time it takes to change from non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

T_f is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.1.2. Normally White Type (Positive)



Tr is the time it takes to change from non-selected state with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.2. Definition of Contrast Ratio

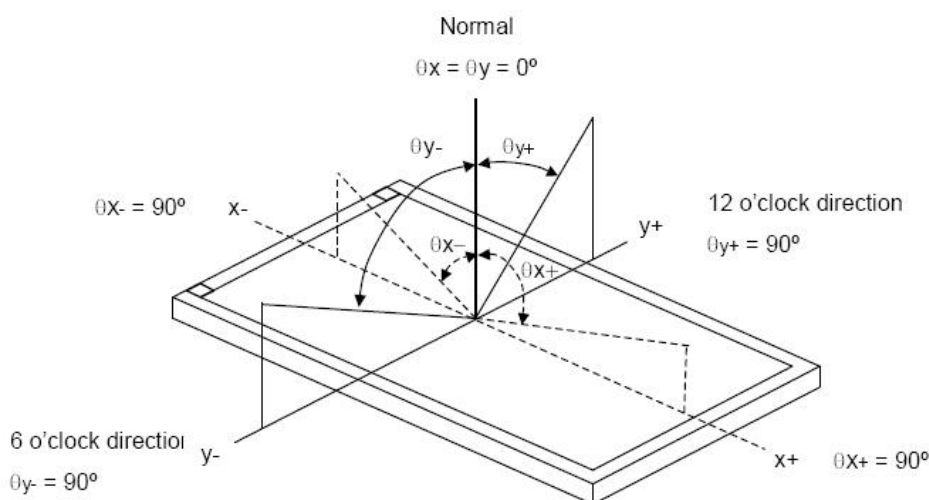
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.3. Definition of Viewing Angles



Measuring machine: LCD-5100 or EQUI

6.4. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.5. Definition of Surface Luminance, Uniformity and Transmittance

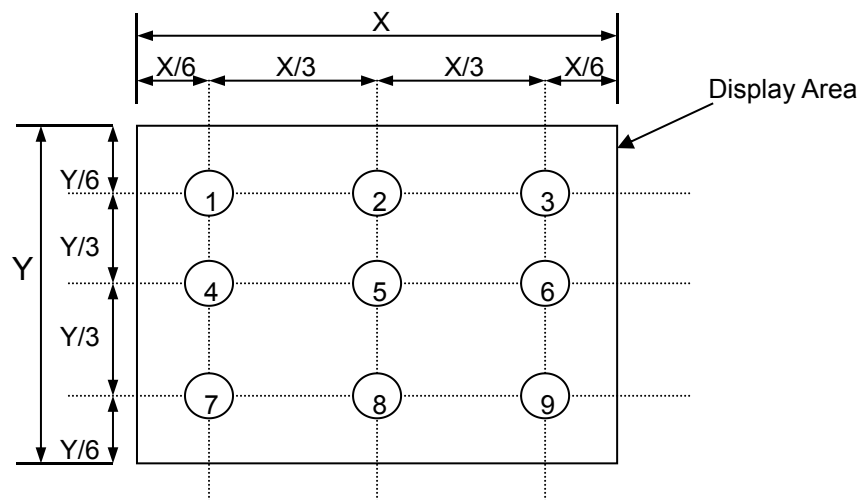
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.5.1. Surface Luminance: $L_V = \text{average } (L_{P1}:L_{P9})$

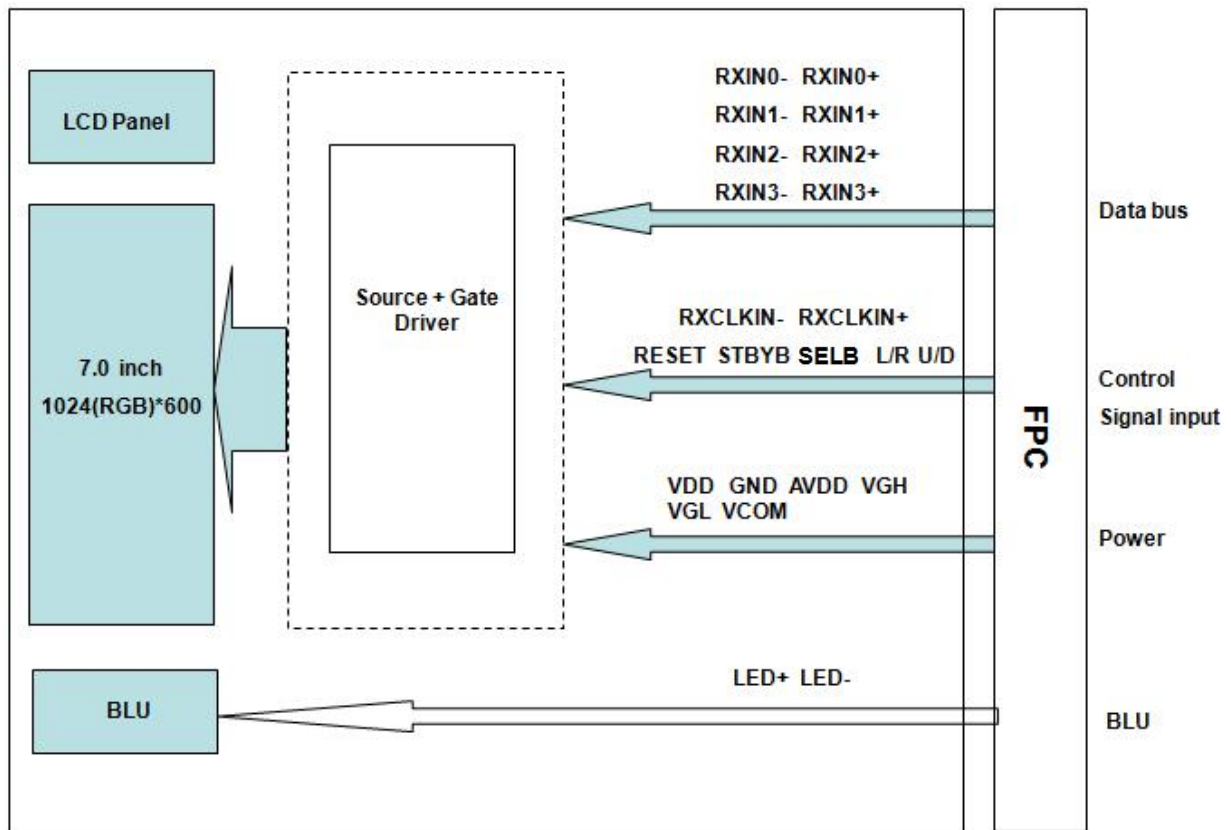
6.5.2. Uniformity = Minimal ($L_{P1}:L_{P9}$) / Maximal ($L_{P1}:L_{P9}$) * 100%

6.5.3. Transmittance = $L_V \text{ on LCD} / L_V \text{ on Backlight} * 100\%$

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



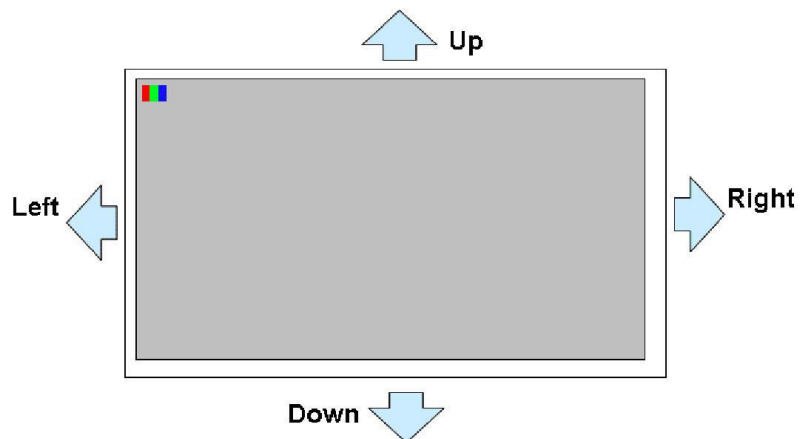
8. Interface Pins Definition

No.	Symbol	Function	Remark
1	VCOM	Common Voltage.	
2	VDD	Power Supply	
3	VDD	Power Supply	
4	NC	Not connected	
5	RESET	Global reset pin	
6	STBYB	Standby mode, Normally pulled high. STBYB="1", normal operation STBYB="0", timing controller, source driver will turn off	
7	GND	Ground	
8	RXIN0-	-LVDS differential data input.	
9	RXIN0+	+LVDS differential data input.	
10	GND	Ground	
11	RXIN1-	-LVDS differential data input.	
12	RXIN1+	+LVDS differential data input.	
13	GND	Ground	
14	RXIN1-	-LVDS differential data input.	
15	RXIN+	+LVDS differential data input.	
16	GND	Ground	
17	RXCLKIN-	-LVDS differential clock input.	
18	RXCLKIN+	+LVDS differential clock input.	
19	GND	Ground	
20	RXIN3-	-LVDS differential data input.	
21	RXIN3+	+LVDS differential data input.	
22	GND	Ground	
23	NC	Not connected	
24	NC	Not connected	
25	GND	Ground	
26	NC	Not connected	
27	DIMO	Backlight CABC controller signal output	
28	SELB	"L": 8bit LVDS interface "H": 6bit LVDS interface	
29	AVDD	Power for Analog Circuit	
30	GND	Ground	
31	LED-	LED Cathode.	
32	LED-	LED Cathode.	
33	L/R	Horizontal inversion.	NOTE1
34	U/D	Vertical inversion.	NOTE1
35	VGL	Gate OFF Voltage.	
36	NC	Not connected	
37	NC	Not connected	
38	VGH	Gate ON Voltage.	

39	LED+	LED Anode.	
40	LED+	LED Anode.	

Note 1:

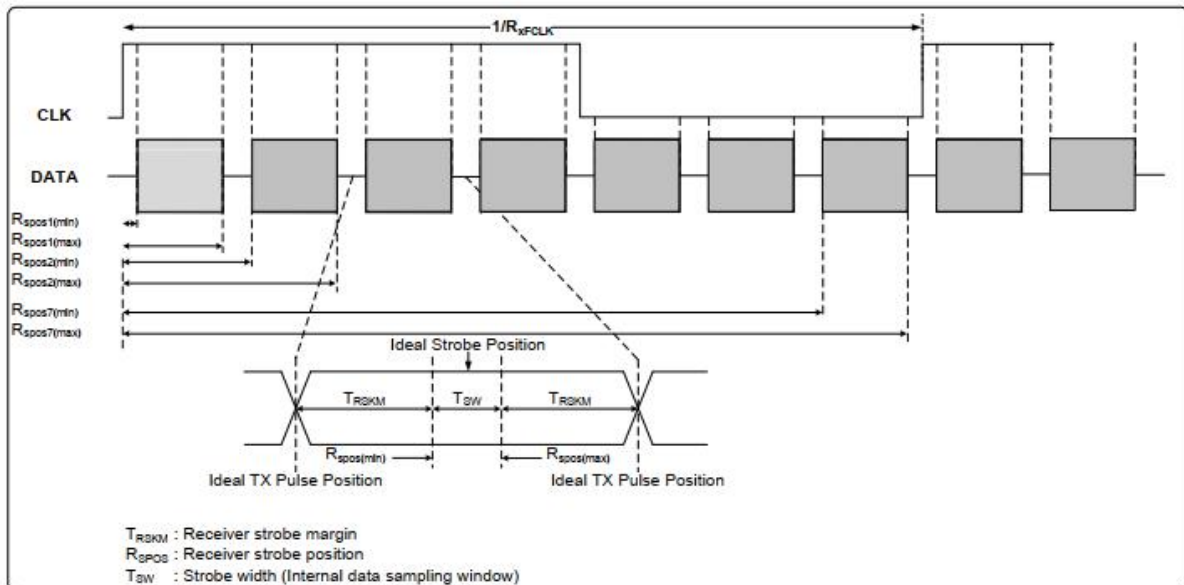
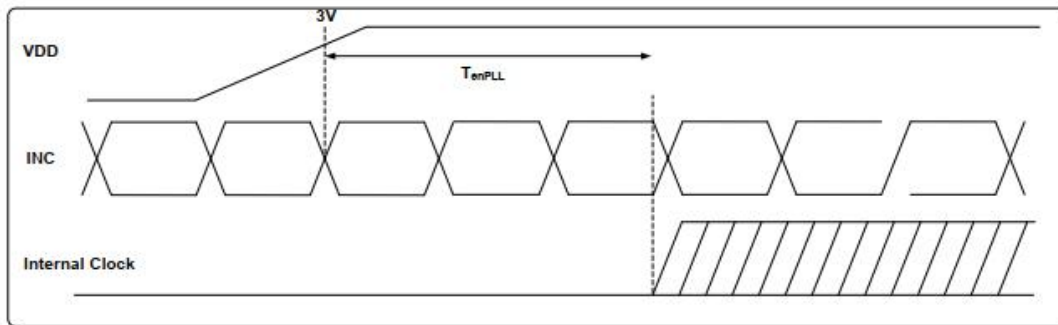
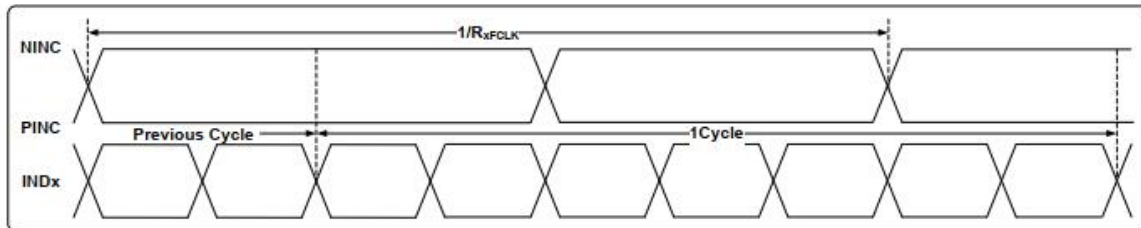
SHLR	UPDN	Data shifting
DVDD	GND	Left→Right , Up→Down(default)
GND	GND	Right→Left , Up→Down
DVDD	DVDD	Left→Right , Down→Up
GND	DVDD	Right→Left , Down→Up



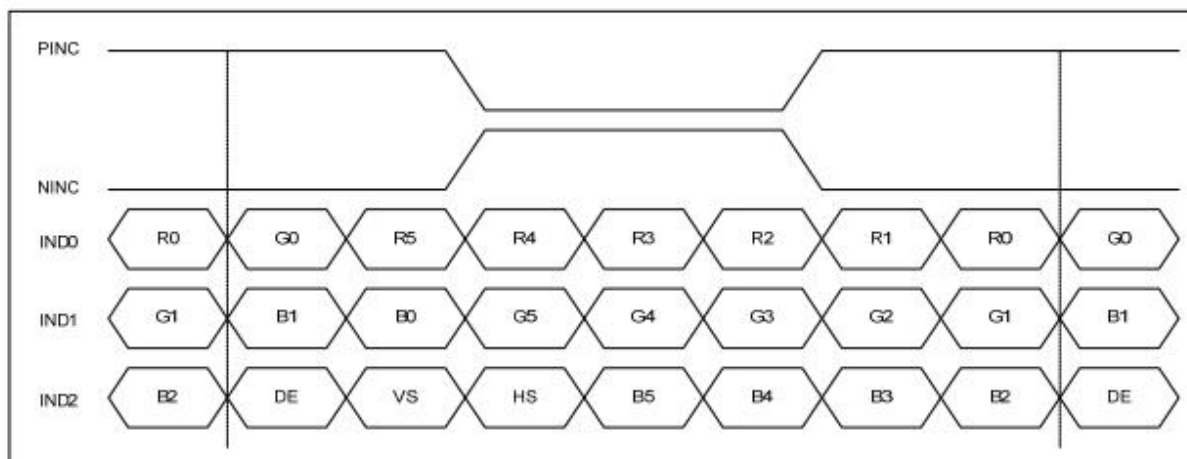
9. AC characteristics

9.1. Timing

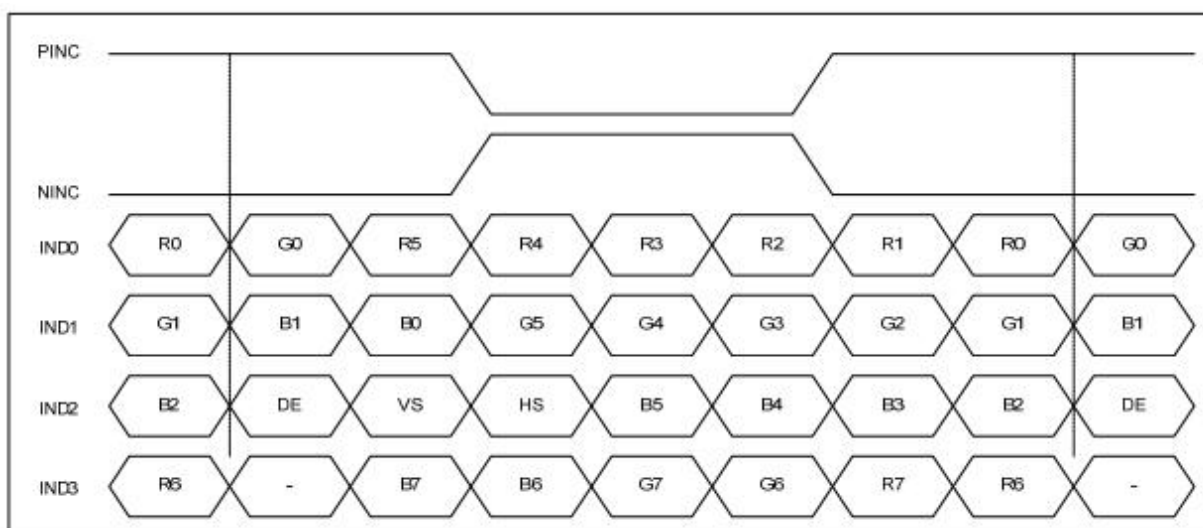
Parameter	Symbol	Condition	Spec.			Unit
			Min.	Typ.	Max.	
Clock frequency	R_{XFCLK}	-	20	-	71	MHz
Input data skew margin	T_{RSKM}	$ V_{ID} =400\text{mV}$ $R_{XVCM}=1.2\text{V}$ $R_{XFCLK}=71\text{MHz}$	500	-	-	pS
Clock high time	T_{LVCH}	-	-	$4/(7 \times R_{XFCLK})$	-	ns
Clock low time	T_{LVCL}	-	-	$3/(7 \times R_{XFCLK})$	-	ns
PLL wake-up time	T_{enPLL}	-	-	-	150	μs



9.2. Data Input Format for LVDS



6 bit LVDS



8 bit LVDS

9.3. Parallel RGB input timing table

DE mode

Parameter	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
DCLK frequency	fclk	40.8	51.2	67.2	MHz
Horizontal display area	thd		1024		DCLK
HSD period	th	1114	1344	1400	DCLK
HSD blanking	thb+thfp	90	320	376	DCLK
Vertical display area	tvd		600		T _H
VSD period	tv	610	635	800	T _H
VSD blanking	tvbp+tvfp	10	35	200	T _H

HV mode

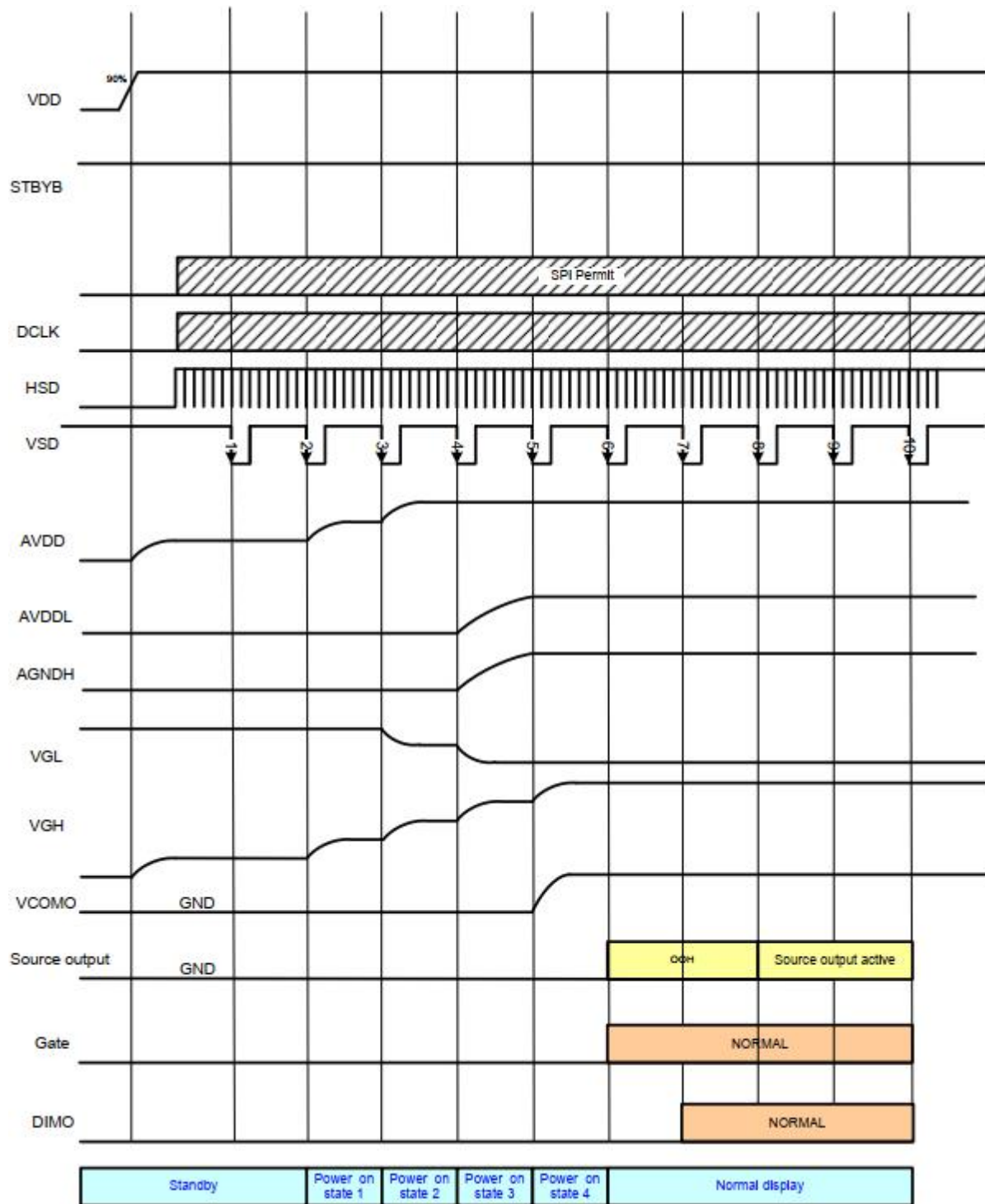
- Horizontal timing

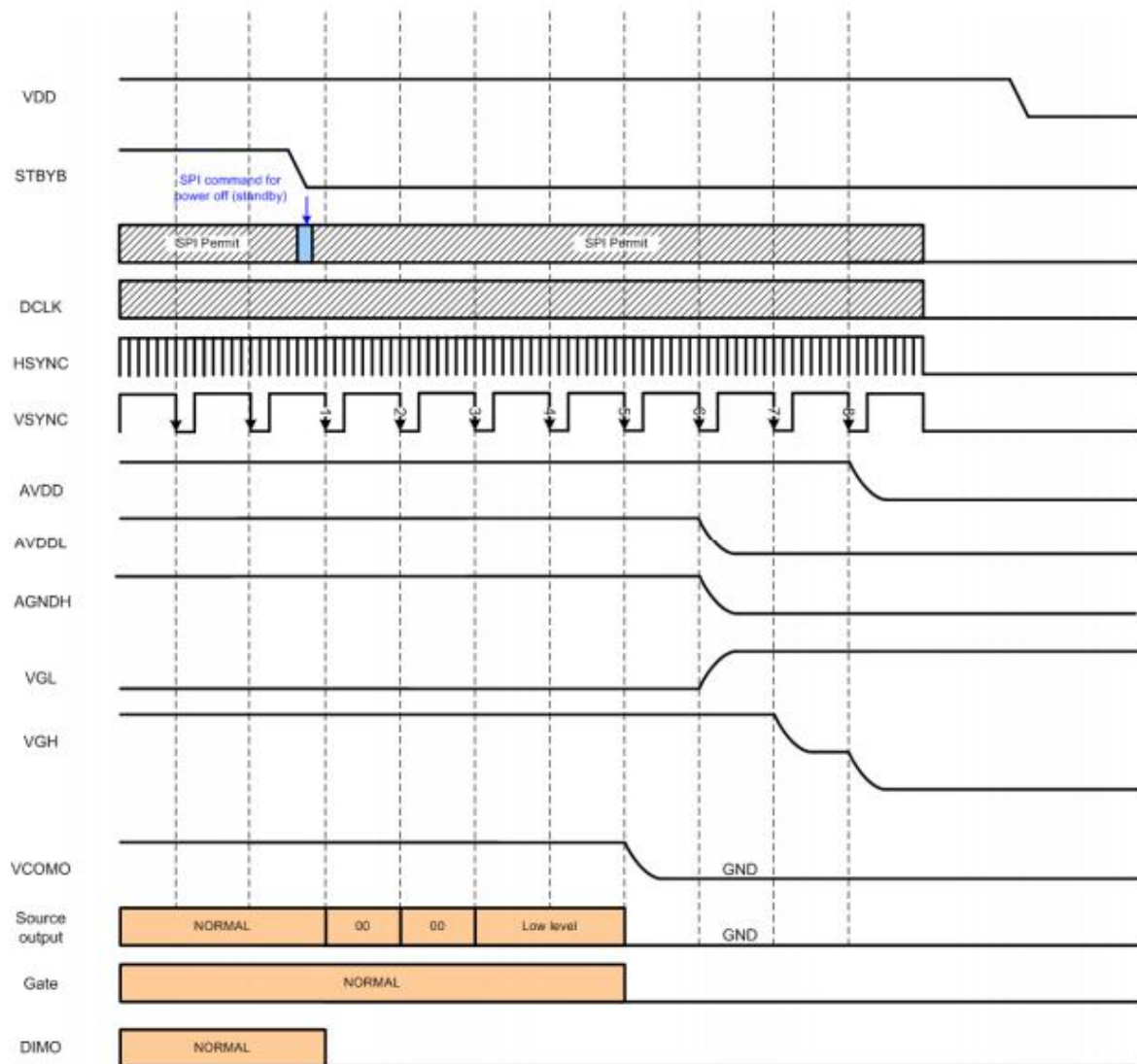
Parameter	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
DCLK frequency	fclk	44.9	51.2	63	MHz
Horizontal display area	thd	1024			DCLK
HSD period th 1200 1344 1400 DCLK					
HSD pulse Width	thpw	1	-	140	DCLK
HSD back porch	thbp	160			DCLK
HSD front porch	thfp	16	160	216	DCLK

- Vertical timing

Parameter	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
Vertical display area tvd 600 T					H
VSD period	tv	624	635	750	T _H
VSD pulse width	tvpw	1	-	20	T _H
VSD back porch	tvbp	23			T _H
VSD front porch	tvfp	1	12	127	T _H

10. Power On/Off Sequence





Note: (1) Low level=3FH, when NBW=L. **(Normally white)**
 (2) Low level=00H, when NBW=H. **(Normally black)**

11. Quality Assurance

11.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

11.2.Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

11.3.Nonconforming Analysis & Disposition

11.3.1. Nonconforming analysis:

11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

11.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

11.3.2. Disposition of nonconforming:

11.3.2.1. Non-conforming product over PPM level will be replaced.

11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

11.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

11.4.1. There is any discrepancy in standard of quality assurance.

11.4.2. Additional requirement to be added in product specification.

11.4.3. Any other special problem.

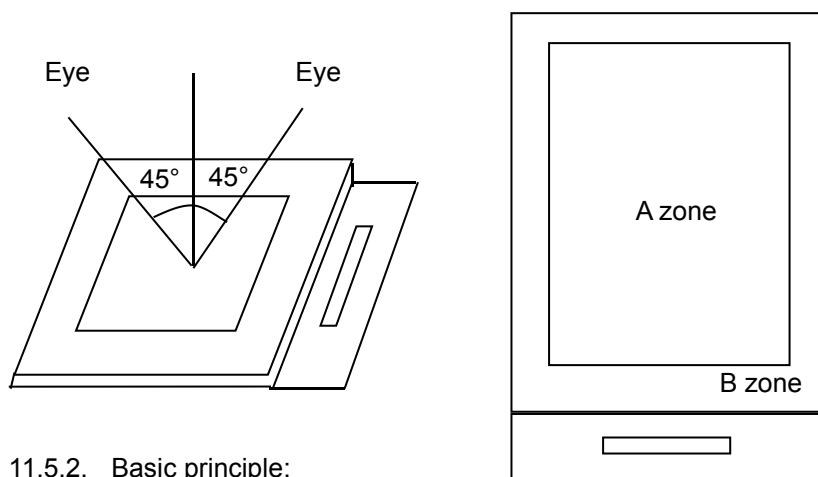
11.5.Standard of the Product Visual Inspection

11.5.1. Appearance inspection:

11.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

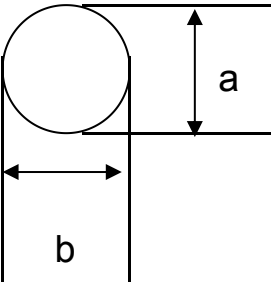


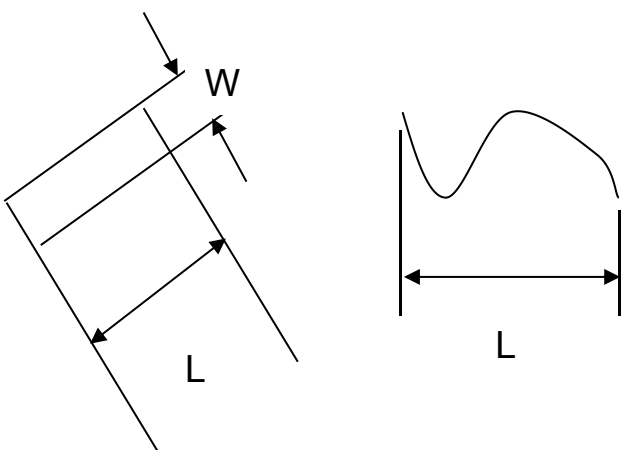
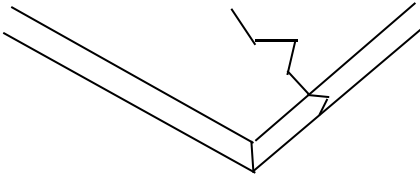
11.5.2. Basic principle:

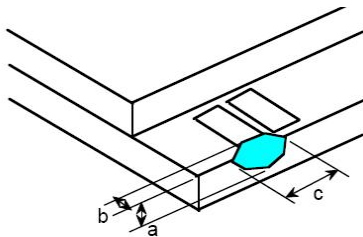
11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

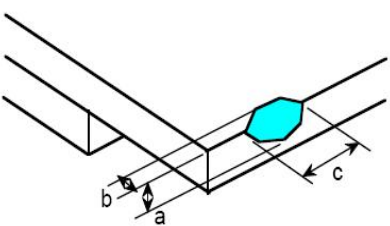
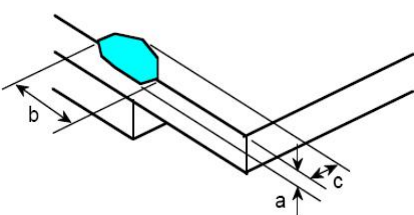
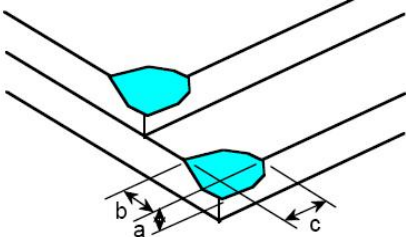
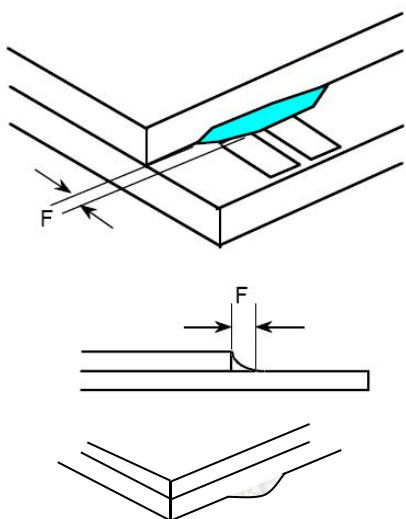
11.5.2.2. New item must be added on time when it is necessary.

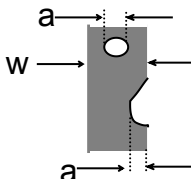
11.6. Inspection Specification for the TFT module

No.	Item	Criteria (Unit: mm)																		
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	 $\phi = (a + b) / 2$ Distance between 2 defects should more than 5mm apart.	<table><tr><th>Size \ Area</th><th>Acc. Qty</th></tr><tr><td>$\phi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \phi \leq 0.50$</td><td>$N \leq 3$</td></tr><tr><td>$0.50 < \phi$</td><td>0</td></tr></table>		Size \ Area	Acc. Qty	$\phi \leq 0.20$	Ignore	$0.20 < \phi \leq 0.50$	$N \leq 3$	$0.50 < \phi$	0								
			Size \ Area	Acc. Qty																
$\phi \leq 0.20$	Ignore																			
$0.20 < \phi \leq 0.50$	$N \leq 3$																			
$0.50 < \phi$	0																			
02	Electrical Defect (Minor defect)	<table><tr><td rowspan="2">Bright dot</td><td>Display Area</td><td>Total</td><td rowspan="2">Note1</td></tr><tr><td>$N \leq 2$</td><td>$N \leq 2$</td></tr><tr><td>Dark dot</td><td>$N \leq 4$</td><td>$N \leq 4$</td><td rowspan="2">Note 2</td></tr><tr><td>Total dot</td><td>$N \leq 4$</td><td>$N \leq 4$</td></tr><tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td><td></td></tr></table>		Bright dot	Display Area	Total	Note1	$N \leq 2$	$N \leq 2$	Dark dot	$N \leq 4$	$N \leq 4$	Note 2	Total dot	$N \leq 4$	$N \leq 4$	Mura	Not visible through 5% ND filters.		
		Bright dot	Display Area		Total	Note1														
$N \leq 2$	$N \leq 2$																			
Dark dot	$N \leq 4$	$N \leq 4$	Note 2																	
Total dot	$N \leq 4$	$N \leq 4$																		
Mura	Not visible through 5% ND filters.																			
		Remark: 1. Bright dot caused by scratch and foreign object accords to item 1.																		

03	Black and White line Scratch Foreign material (Line type) (Minor defect)	 <table border="1" data-bbox="577 748 1203 1012"> <thead> <tr> <th>Length</th><th>Width</th><th>Acc. Qty</th></tr> </thead> <tbody> <tr> <td>/</td><td>$W \leq 0.1$</td><td>Ignore</td></tr> <tr> <td>$L \leq 2.5$</td><td>$0.1 < W \leq 0.2$</td><td>3</td></tr> <tr> <td>$L > 2.5$</td><td>$0.2 < W$</td><td>0</td></tr> <tr> <td colspan="2">Total</td><td>3</td></tr> </tbody> </table> Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.	Length	Width	Acc. Qty	/	$W \leq 0.1$	Ignore	$L \leq 2.5$	$0.1 < W \leq 0.2$	3	$L > 2.5$	$0.2 < W$	0	Total		3
Length	Width	Acc. Qty															
/	$W \leq 0.1$	Ignore															
$L \leq 2.5$	$0.1 < W \leq 0.2$	3															
$L > 2.5$	$0.2 < W$	0															
Total		3															
04	Glass Crack (Minor defect)	 Crack is potential to enlarge, any type is not allowed.															

05	Glass Chipping Pad Area: (Minor defect)		<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>3</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$	
	Length and Width	Acc. Qty									
$c > 3.0, b < 1.0$	1										
$c < 3.0, b < 1.0$	3										
$a < \text{Glass Thickness}$											

06	Glass Chipping Rear of Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
07	Glass Chipping Except Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
08	Glass Corner Chipping: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 3.0, b < 3.0$</td><td>Ignore</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												
09	Glass Burr: (Minor defect) 	<table><tr><th>Length</th><th>Acc. Qty</th></tr><tr><td>$F < 1.0$</td><td>Ignore</td></tr></table> Glass burr don't affect assemble and module dimension.	Length	Acc. Qty	$F < 1.0$	Ignore						
Length	Acc. Qty											
$F < 1.0$	Ignore											

10	FPC Defect: (Minor defect) 	10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.								
11	Bubble on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.30$</td><td>Ignore</td></tr><tr><td>$0.30 < \varphi \leq 0.50$</td><td>$N \leq 2$</td></tr><tr><td>$0.50 < \varphi$</td><td>$N = 0$</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.30$	Ignore	$0.30 < \varphi \leq 0.50$	$N \leq 2$	$0.50 < \varphi$	$N = 0$
Diameter	Acc. Qty									
$\varphi \leq 0.30$	Ignore									
$0.30 < \varphi \leq 0.50$	$N \leq 2$									
$0.50 < \varphi$	$N = 0$									
12	Dent on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.25$</td><td>Ignore</td></tr><tr><td>$0.25 < \varphi \leq 0.50$</td><td>$N \leq 4$</td></tr><tr><td>$0.50 < \varphi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.25$	Ignore	$0.25 < \varphi \leq 0.50$	$N \leq 4$	$0.50 < \varphi$	None
Diameter	Acc. Qty									
$\varphi \leq 0.25$	Ignore									
$0.25 < \varphi \leq 0.50$	$N \leq 4$									
$0.50 < \varphi$	None									
13	Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.								
14	PCB	14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.								
15	Soldering	Follow IPC-A-610C standard								
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.								

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

11.7. Classification of Defects

11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

11.7.2. Two minor defects are equal to one major in lot sampling inspection.

11.8. Identification/marketing criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

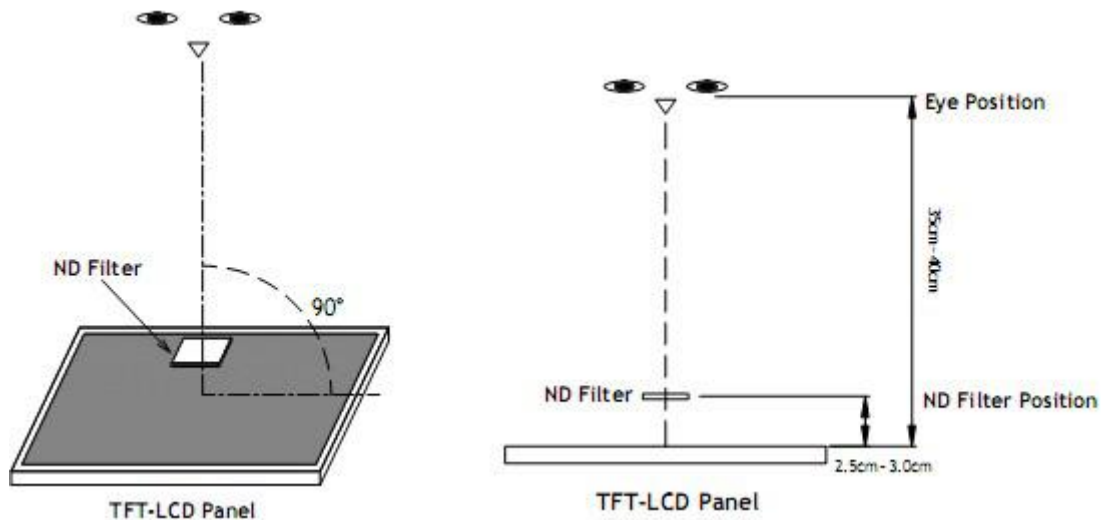
11.9. Packing

11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.

11.9.2. Modules inside package box should have compliant mark.

11.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

12. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1-2008
3	High Humidity Storage	60°C, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test Storage	-20°C, 60min ~ 70°C, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14-2009
8	Electrical Static Discharge	Air: ±4KV 150pF/330 Ω Contact: ±2KV 150pF/330 Ω	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height:72cm(weight ≤ 10kg),60cm (weight > 10kg) 1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8-1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

13. Precautions and Warranty

13.1.Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

13.2.Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

13.3.Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter

13.4.Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

- 13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

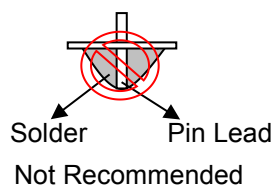
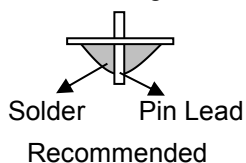
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



13.4.2. Pins of EL

- 13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

- 13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290℃

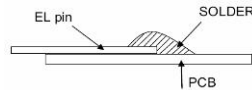
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

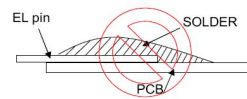
- 13.4.2.4. No horizontal press on the EL leads during soldering.

- 13.4.2.5. 180° bend EL leads three times is not allowed.

13.4.2.6. Solder Wetting

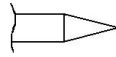


Recommended

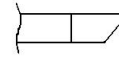


Not Recommended

13.4.2.7. The type of the solder iron:

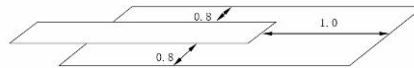


Recommended



Not Recommended

13.4.2.8. Solder Pad



13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it may develop image sticking due to the TFT structure.

13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

13.7. Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

14. Packaging

TBD

15. Outline Drawing

